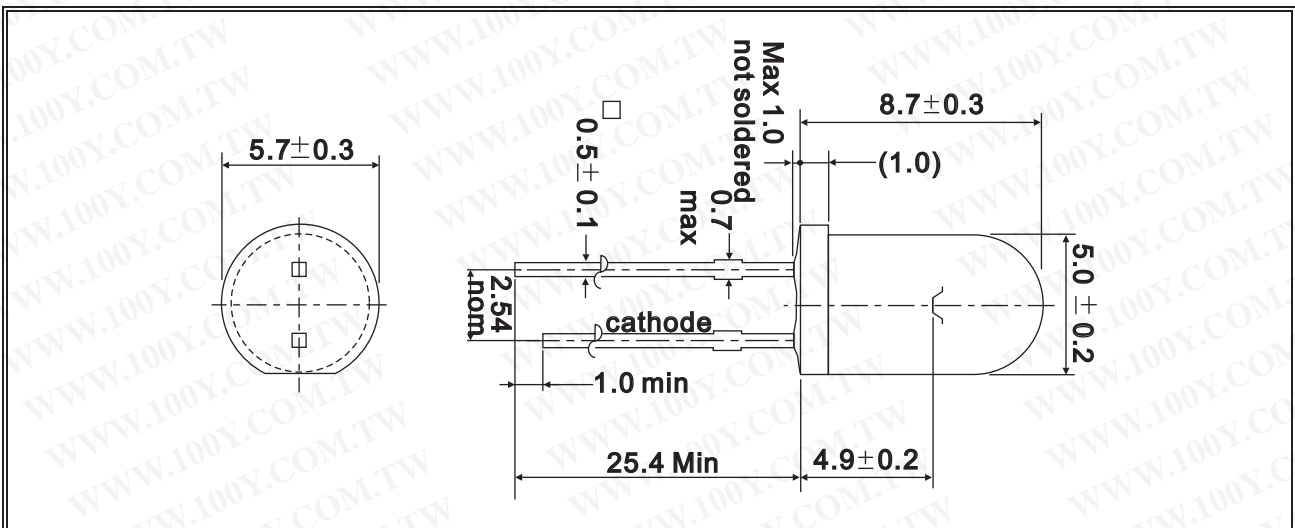


DEVICES

Part Number	Lens		Source	
	Color	Diffusion	Dice Source	Color
HIRB5-43L1-C	Water Clear	Non-Diffused	GaAlAs/GaAlAs	Infrared

PACKAGE DIMENSIONS:



NOTE:

- 1.All dimensions are in millimeter.
- 2.Lead spacing in measured where the lead emerge from the package.
- 3.prodruded resin under flange is 1.5mm max.
- 4.specifications are subject to change without notice.
- 5.Tolerance is  $\pm 0.3$ mm unless otherwise noted.

ABSOLUTE MAXIMUM RATINGS

TA=25°C

PARAMETER	SYMBOL	MAX. RATING	UNIT
Power Dissipation	Pd	390	mW
Continuous Forward Current	IF	150	mA
Peak Forward Current *1	IFM	1.0	A
Reverse Voltage	VR	4	V
LED Junction Temperature	Tj	100	°C
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Dip Soldering Temperature (3mm from case Bottom 260 °C for 5 seconds)			

\*1.Duty Ratio=0.1%,Pulse Width=10us.

\*2.Iron soldering in 350°C within 5 seconds will not cause damage to the dice. But be aware of the high temperature will not only make the epoxy soften but also cause the lead moving and the gold wire broken and even open. So before returning to the normal temperature PLEASE AVOID any serious pressure on the top of epoxy and lead.

ELECTRIC-OPTICAL CHARACTERISTICS

TA=25°C

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
View Angle of Half Power	2θ1/2	IF=150mA		35		deg
Forward Voltage	VF			1.7	2.1	V
Reverse Current	IR	VR=4V			10	μA
Luminous Intensity *2	IV	IF=150mA	150	300		mw/sr
Peak Emission Wavelength	λp			850		nm
Spectrum Width Of Half Valve	Δλ			45		nm
Rise/Fall Time	Tr/Tf			30		ns
Terminal Capacitance	Ct	V=0V F=1MHz		70		pF

\*2.Tolerance:±15% HUEY-JANN measuring equipment : EXELTRON 2001. 2.S370 made by U.D.T.

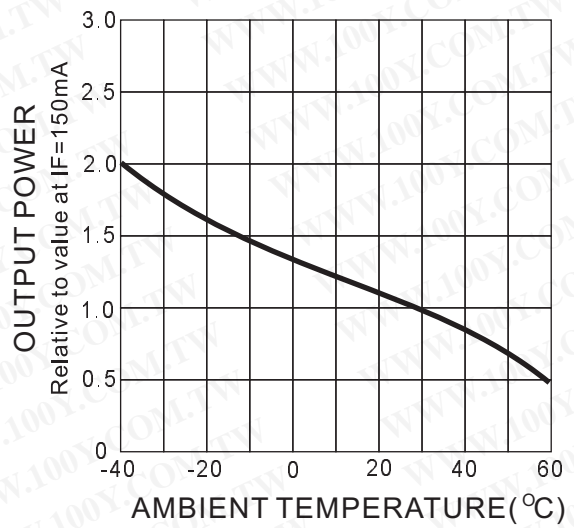
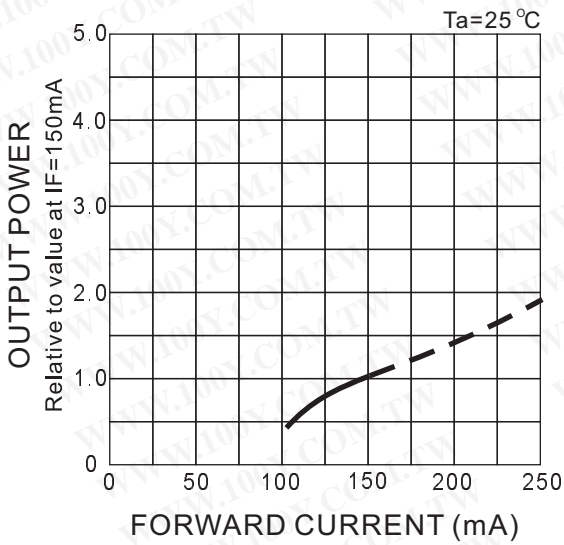
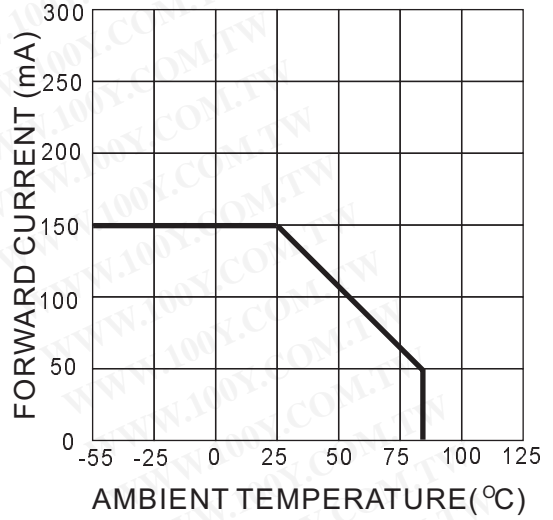
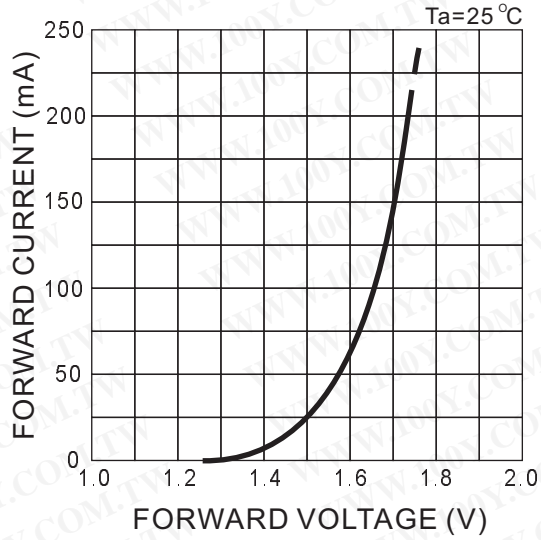
RELIABILITY TEST

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	Connect with a power if=150mA Ta=Under room temperature Test Time=1,000hrs	0/22
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+85°C±5°C RH=90% ~ 95% Test Time=1000hrs	0/22
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+100°C±5°C Test Time=1,000hrs	0/22
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-40°C±5°C Test Time=1,000hrs	0/22
	Environmental Test	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-40°C ~ +25°C ~ +85°C ~ +25°C 60min 20min 60min 20min Test Time=200cycle
Thermal Shock		MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010	-40°C±5°C ~ +85°C±5°C 20min 20min Test Time=200cycle	0/22

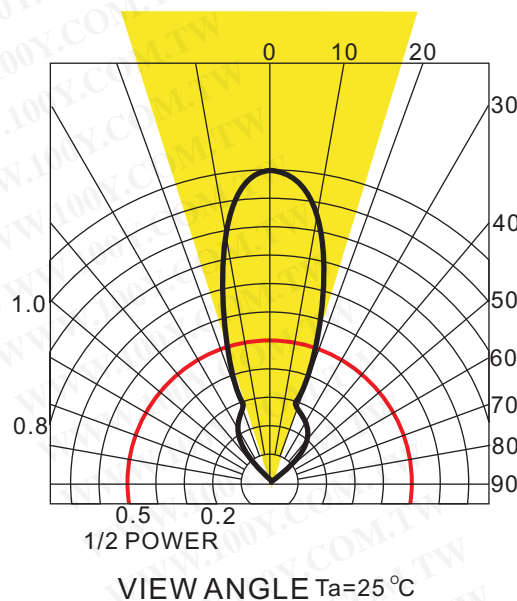
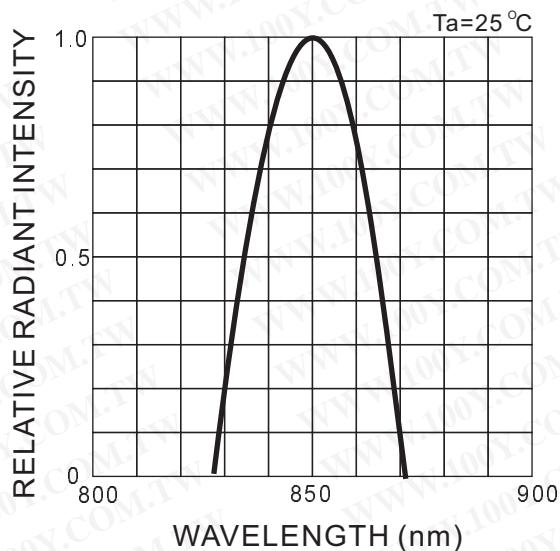
\*Failure Criteria:

1. VF arise  $\geq$  10%
2. IV decline  $\geq$  30%
3. A failure is an LED that is open or shorted

TYPICAL ELECTRICAL OPTICAL CHARACTERISTICS CURVES



TYPICAL ELECTRICAL OPTICAL CHARACTERISTICS CURVES



LED VF Bin Selection

$I_F=150\text{mA}$

BIN CODE	Forward Voltage	
	Minimum	Maximum
b	1.4	1.6
c	1.6	1.8
d	1.8	2.0
e	2.0	2.2

Voltage tolerance for each bin limit is  $\pm 0.03\text{V}$

Brightness Bin Selection

$I_F=150\text{mA}$

BIN CODE	Radiant Output Power (mw/sr)	
	Minimum	Maximum
9	140	200
10	200	280
11	280	360
12	360	440

Tolerance for each bin limit is  $\pm 15\%$